- **1** Development of intermediate layer systems for direct
- 2 deposition of thin film solar cells onto low cost steel

# **3 substrates**

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# Abstract

13 The functionalisation of low-cost steel over large areas with low cost intermediate layers (ILs) 14 for utilisation as substrates in thin film solar modules is reported. Three approaches for the deposition of ILs are demonstrated and evaluated; a thick SiO<sub>x</sub> sol-gel based on a one-step acidic 15 16 catalysis applied by spray technique, a commercial screen-printable dielectric ink, and an epoxy-17 based material (SU8) deposited by screen printing or bar coating. These ILs demonstrated the properties of surface levelling (quantified by mechanical profilometry), electric insulation (tested 18 19 using breakdown voltage and leakage current) and acted as an anti-diffusion barrier (demonstrated 20 with glow discharge mass spectrometry). Moreover, the performances of amorphous silicon (a-21 Si:H) and organic photovoltaic (OPV) thin film solar cells grown on carbon and stainless steels 22 (a-Si:H: 5.53% and OPV: 2.40%) show similar performances as those obtained using a reference glass substrate (a-Si:H: 5.51% and OPV: 2.90%). Finally, a cost analysis taking into account both 23 24 the  $SiO_x$  sol-gel and the dielectric ink IL was reported to demonstrate the economic feasibility of 25 the steel/IL prototypes.

### 27 **1. Introduction**

Building Integrated Photovoltaics (BIPV) has emerged as an important strategy for 28 domestic energy production with commercial interest driven by the EU's 2020 targets [1, 29 2] and the consideration that all new buildings should be nearly zero-energy by the end 30 of 2020. Although BIPV still represents a small share of the photovoltaic (PV) market, a 31 number of demonstrators have shown the feasibility of BIPV systems and their superiority 32 over conventional roof installation (Building Attached Photovoltaics (BAPV)) 33 34 approaches in terms of overall cost and aesthetics [3, 4]. BIPV concepts have been applied 35 within a diverse range of building sector products including for public/commercial and domestic buildings, both for retrofitting and for new buildings (see, for example, [5]). 36

Most BIPVs are made using silicon-based materials; however, further improvements in product innovation and cost are still required in order to compete with mainstream PV technologies. As a result a number of different authors [6, 7, 8, 9] have proposed: (i) the integration of thin film solar cells (TFSC) as alternatives to crystalline silicon (c-Si), and (ii) the development of BIPVs directly onto conventional building materials instead of glass substrates.

In order to introduce the TFSC technology in the market in a competitive fashion, a 43 44 number of challenges need to be overcome. Firstly, there is a need to demonstrate the 45 feasibility of low-cost substrates that are already using by the construction industry; for example to adopt steel substrates, low cost alternatives are need as existing work is based 46 on expensive "solar-grade" stainless steel (SS), which is too costly for the construction 47 industry. Therefore, it is more cost effective if existing construction material is adapted 48 for BIPV usage, but this requires specific preparation of the steel surface. The preferred 49 50 solution is the use of an intermediate layer (IL) system between the steel and the TFSC. The steel industry has substantial experience of coating insulating layers so this is a 51 52 feasible option for implementation. The main requirements for this IL layer are: (i) to smooth the steel surface in order to prepare it for the application of TFSC nanolayers and 53 to prevent direct short-cuts in the future integrated solar cells; (ii) to prevent the diffusion 54 of chemical elements (e.g. Fe, Cr, Ni, etc.) from the steel to the TFSC during the solar 55 56 cell process fabrication; (iii) to electrically insulate the TFSC back contact electrode from 57 the steel substrate to allow the development of TFSC modules by the interconnection of monolithic serial cells using laser ablation scribing processes; and (iv) to be stable and 58

not delaminate during post-processing for semiconductor layer deposition as well asduring storage.

Recently, several works concerning IL system deposition on steel substrate to develop 61 chalcopyrite (CIGS) or silicon TFSC have been reported. Whilst promising, their work 62 63 used relatively thin IL which are unlikely to be scalable for solar modules. L. Zortea et al. [10] investigated the behavior of an electroplated bi-layer (Ni and Cr) on a mirror 64 surface finished (average roughness, R<sub>a</sub> <0.1µm) mild steel foil. Kyoung-Bo et al. [11] 65 developed monolithic CIGS on SS applying, by screen-printing, a 10µm silicon dioxide 66  $(SiO_2)$  IL. However, the resulting R<sub>a</sub> was 0.21 $\mu$ m and only poor levelling was achieved 67 through the sol-SiO<sub>2</sub> ( $R_a=0.157\mu m$ ). Thongkham *et al.*[12] applied aluminum oxide 68 69 (Al<sub>2</sub>O<sub>3</sub>) (2µm thick) by physical vapour deposition (PVD) on different SS substrates 70 (types 301, 316L and 430) and reported a very poor adhesion due to the different 71 coefficient thermal expansions (CTE) of the IL compared to the CIGS thin films.

Concerning silicon based TFSC, Yun et al. [13] developed SiO2 and Al2O3/SiO2 sol-gel 72 73 stack as IL for SS. The results showed poor adhesion of the layers and etching the surface 74 with hydrochloric (HCl) acid solution prior to application of the IL was needed to increase the roughness and improve the adhesion. Lee et al. [14] reported the improvement of the 75 76 performance of silicon TFSC on SS substrate by an electrochemical mechanical polishing 77 method. This process created chromium oxide (Cr<sub>2</sub>O<sub>3</sub>) and iron oxide (Fe<sub>2</sub>O<sub>3</sub>) passive films which act as anti-diffusion layers, blocking Cr and Fe diffusion into the silicon 78 TFSC. However, electrical insulation was not achieved using these passive films. 79 80 Martinez et al [9] developed a  $SiO_x$  sol-gel multilayer to make automotive hot-dip galvanized steel compatible with amorphous silicon (a-Si:H) TFSC. A power conversion 81 82 efficiency (PCE) of 3.03% was achieved, but the scalability to larger areas was not addressed. Lopez et al [15] combined SiO<sub>x</sub> sol-gel and SiO<sub>x</sub> plasma enhanced chemical 83 84 vapor deposition (PECVD) films in two and three layers stacks on SS foils, reporting highly dielectric properties (breakdown voltages > 900V) and compatibility with CIGS 85 TFSCs. 86

In general, CIGS and silicon-based thin film technologies are the most widely reported and mature PV systems which have been developed onto steel substrates, although there have also been some attempts with dye sensitized [16], cadmium tellurite [17], organic photovoltaic (OPV) [18-21], and kesterite solar cells [22]. Many of the reports, such as Ding *et al* [21] were focused on non-scalable approaches to IL deposition for OPVs using spin-coating. As OPVs are likely to made commercially by roll-to-roll (R2R) production
methods, similar processing strategies must be adopted for the application of ILs.

As can be seen in the works above, steel/IL systems show several drawbacks for an
industrial application, such as the necessity to process the steel surface to reach a very
low roughness [10, 14], poor IL adhesion [12, 13], the lack of electrical insulation [14],
and the difficulty in implementing multilayer stacks [9, 15].

- Moreover, most of these examples use relatively expensive steels (e.g. stainless and only very thin substrates, around 25µm thick), and in most of these cases the up-scaling of the process in terms of manufacturing yield, potential or cost is rarely reported. This creates a paradoxical situation; by using an expensive steel substrate, the end product is difficult to be introduced to the building sector, as it is more common to use a lower cost steel such as dipped or galvanised low carbon steels for building infrastructure.
- In this paper several low-cost IL strategies (ceramic sol-gel and polymer-based) deposited onto low-cost structural steel grades are reported. The developments were carried out with the view to possible further industrial application, so only single layer IL strategies were pursued to make compatible steel substrates and TFSC. In that sense, one challenge of the present work concerned the sol-gel IL, as its main drawback is that its maximum achievable thickness without stress cracks forming is low (typically, 1µm).
- 110 In addition, only high throughput coating techniques were employed in order to 111 demonstrate the potential for upscaling the approach. The IL systems were characterised 112 morphologically and electrically, and different TFSC (a-Si:H and OPV) were grown and 113 compared with glass substrates as reference to demonstrate the feasibility of our approach for the thin-film solar community. The results show that the behaviour of amorphous 114 115 silicon cells and OPVs on intermediate layers of SiOx sol-gel and SU8, respectively, are 116 indistinguishable from cells grown on glass, which constitutes the most innovative part 117 of this work.

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119 **2. Experimental** 

### 120 2.1 Substrate selection

121 The initial selection of steel substrates has been made by consideration of four main 122 factors: (i) chemical inertness, (ii) thermal coefficient of expansion with respect to the IL materials, (iii) surface quality in terms of absence of defects and low initial roughness,and (iv) pre-existing usage within the construction sector.

125 Four steels were selected which met these criteria: a bare low carbon steel (DC01), two 126 hot-dipped metallic low carbon steels (zinc-coated DX51D+Z and aluminium-silicon 127 coated DX51D+AS) and a ferritic stainless steel (AISI430). Chemical composition of each type is given in Table I. Initially, all the steels were rolled by high speed steel (HSS) 128 129 grinding rolls in order to reduce the initial peak to-peak  $(R_z)$  surface roughness down to 130 1.3 µm. This roughness value was considered as a good compromise between the rolling cost and the intermediate layer approach considered. The steels were rolled to a thickness 131 of 0.3mm as this is compatible with lab-scale coating techniques and leads to a 10 times 132 133 reduction in the steel costs when compared to the industrial standard stainless steel used 134 in previous attempts to integrate steel and TFSCs [23].

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### 136 **2.2** Intermediate layer (materials, processes and characterization)

Once the steel substrates were prepared, ILs were applied to fulfil the following 137 138 requirements: (i) to level and minimize the surface roughness for high quality thin film 139 solar deposition, (ii) to electrically isolate the steel substrate for safety and to enable monolithic integration, (iii) to act as a barrier for ionic diffusion and to avoid TFSC 140 141 contamination from the steel, (iv) to give thermal and mechanical stability to the PV cell or module above the steel substrate, (v) to show a long shelf life during storage, and (vi) 142 143 to be compatible with subsequent PV deposition processes. The selected ILs and the deposition methods are listed below: 144

### 145 2.2.2 SiO<sub>x</sub>-based sol-gel coatings

#### 146 **2.2.2.1 Sol-gel synthesis**

Sol-gel is a well-established technology for thin-film coatings in the steel industry; materials are applied in a mixture that leads to a hydrolysis-condensation of the precursors and enables coatings through low cost/temperature deposition techniques. Sol-gel technology offers a good control of the thickness and a high degree of homogeneity through the creation of an inorganic matrix. The main drawback for sol-gel is that its maximum achievable thickness without stress cracks forming is low (typically, 1µm). Cracks are mainly produced during evaporation of solvents due to mechanical and

thermal stresses between the layer and the substrate. The introduction of tension releasing 154 agents in sol-gel matrixes constitutes an interesting approach to reduce cracking and 155 increase coating thickness. Special attention to this strategy has been considered in this 156 157 work. In this work, the sol-gel formulation followed a one-step acid catalysis using 158 methyltriethoxysilane (MTES 99%, Aldrich) and tetraethyl orthosilicate (TEOS 98%, Aldrich) as precursors. Water was incorporated as a solvent, polyethylene glycol 6000 159 160 (PEG-6000, Panreac) as a tension releasing agent and HNO3 as a catalyst. The molar ratios were optimised in order to reach a suitable homogeneity, adhesion and pin-hole 161 162 free layer after application and curing. These were TEOS/MTES: 1.35, H<sub>2</sub>O/(MTES+TEOS): 4.7, and PEG-6000/(MTES+TEOS): 0.02. The synthesis was 163 164 carried out at room temperature with vigorous magnetic stirring. The addition of HNO<sub>3</sub> initiates the hydrolysis, increasing the temperature by 25°C. During the sol phase 165 166 preparation, the ambient conditions have been controlled, being the average temperature registered of 23°C and the relative humidity of 48%. This sol mixture was aged for one 167 168 hour under stirring before application.

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### 170 2.2.2.2 Sol-gel deposition and curing

Spray coating was performed with a commercial air atomizing spray gun (Spraying Systems Inc.) with a nozzle cone angle of  $60^{\circ}$ . It was mounted on an automatized spray system and moved transversely with respect to the sample movement. The 30cm x 30cm samples were coated using the following parameters: (i) SiO<sub>x</sub> sol-gel dilution 1:0.5 in ethanol, (ii) a sol-gel liquid pressure between 0.4bar and 0.5bar, (iii) a holder speed of 1.6m/min, (iv) a nozzle/sample distance of 8cm, and (v) a one scan spray.

177 Curing was carried out by means of near-infrared (NIR) technique. The fast heating of the steel substrate combined with the relative transparency of the sol-gel film to NIR 178 179 radiation allows a rapid, indirect annealing of the sol-gel layer. In addition, the prospect of curing from the inner to the outer part of the coating enables a correct extraction of the 180 solvents. The experiments were performed using a NIR equipment (AdPhos, model 336-181 250) composed of eight NIR lamps (0.8kW each) each 250mm x 42mm, which outputs a 182 maximum power density of 76kW/m<sup>2</sup>. The distance between the NIR lamps and the 183 steel/IL prototypes was kept constant at 20cm and the process was developed in sheet-to-184 185 sheet mode. At an irradiation power of 90%, a cure time of 2 minutes was applied in all

cases (reaching a peak metal temperature of 198°C), which represents a clear time
reduction when compared to conventional hot-plate curing (close to one hour, typically).

In order to study the suitability of the sol-gel coatings for the coating of selected steels, 188 189 the surface tension was measured using a Dynamic Absorption and Contact Angle Tester (FIBRO DAT 1100), and showed a value of 26.19±0.14mN/m. Under the same 190 191 experimental technique, the surface free energy of the four steel substrates was also 192 evaluated using the Owens-Wendt-Rabel-Kaelble method. The values obtained were 193 between 38mN/m and 40mN/m for all steel types, and confirm the suitability of the sol formulation for coating onto these steels. Additionally, viscosity has been calculated 194 195 using a Bohlin-Gemini rheometer. The obtained value was 0.005Pa.s at 230 1/s. This 196 ensures the solution is suitable for dip and spray coating technologies and should lead to 197 relatively thin coatings.

#### 198 2.2.3 Organic commercial coatings

Organic coatings have also been trialled as ILs. These materials allow easier processing,
thicker coatings with better dielectric behaviour and potentially better planarization.
Organic materials were sought on the basis of the following priorities: low cost, proven
dielectric properties and usage in other industries i.e. electronics, printability/coatability,
good insulation and good adhesion to substrates. Two materials were trialed:

#### 204 **2.2.3.1 Blue Ink**

Blue Ink is a commercially available dielectric ink also known as 'blue dielectric paste' (D2140114D5) from Sun Chemical, USA. This material was screen printed by means of a sheet-to-sheet semi-automated system (DEK248) suitable for handling 35cm x 35cm (up to 6 mm thick) steel sheets. The layers were applied directly onto the steel through square stencils. After coating, the ink layer was then dried using a hot air conveyor dryer at 150°C for 20 minutes.

#### 211 2.2.3.2 SU-8

SU-8 is an epoxy-based material, which contains a bisphenol A novalac epoxy that is dissolved in cyclopentanone and mixed with 10% of mixed triarylsulfonium salt which acts as the photoacid generator. It is widely used in the microelectronics and micro electro mechanical systems (MEMS) industry as it crosslinks under ultra-violet (UV) irradiation. After coating it can provide a suitable interface between a steel substrate and a PV cell. The SU-8 epoxy layer (the formulation used is SU8-2050, supplied from Chestech ltd.,

218 UK) was bar coated onto the steel samples (size 18mm x18mm). In contrast to the earlier

work of Ding *et al* [21], the SU-8 deposition approach is scalable to larger areas, therefore

potential enabling module production. The film was then cured at 150°C for 15 minutes

then hard baked at 250°C for 10 minutes.

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### 223 2.2.3 Characterization of the steel/IL systems

224 Three main characterization techniques have been considered in this work. Firstly, the 225 impact of the IL on surface roughness, which has been determined through roughness analysis by mechanical profilometry (Model XP-1, Ambios Technology, USA). 226 Profilometry was selected for surface roughness measurements because it allows for 227 surface roughness measurements to be conducted over large areas. A large surface area 228 needs to be mapped because a small number of surface topography issues could lead to 229 electrical shortages. Profilometry allows for large processing anomalies to be identified, 230 231 but also allows for the surface roughness to be accurately characterized as the resolution of our system is 5Å. 232

233 Secondly, the anti-diffusive behaviour of the layer has been characterized by solid state Glow Discharge Time of Flight Mass Spectrometer (GD-ToF-MS). GD sources coupled 234 to MS provides rapid and highly sensitive characterisation of major and trace elements in 235 homogeneous solids as well as depth profiling analysis of coating materials [24]. The 236 radiofrequency (rf) GD-ToFMS instrument consists of a rf-GD bay unit from Horiba 237 238 Jobin Yvon coupled to a fast orthogonal time-of-flight mass spectrometer (Tofwerk) with a microchannel plate detector [25]. A pure copper modified Grimm-type GD source 239 (EMPA), with a 4 mm diameter anode and a 2.5 mm inner diameter flow tube was used. 240 241 The power is supplied to the GD through the back side of the sample by an rf-power generator operating at 13.56 MHz. Experimental conditions (120 Pa argon discharge 242 243 pressure, 70 W rf forward power) were chosen as a compromise between high sensitivity 244 and good depth resolution. Finally, the dielectric behaviour has been analysed. Two approaches were developed. Concerning the breakdown voltage, aluminium (Al) pads 245 (1cm<sup>2</sup>) have been first deposited by thermal evaporation (Pfeiffer, model Classic 500) on 246 the IL using a shadow mask. The tests were then performed varying a voltage in a range 247 of 0V to 53V (using a direct current source) between a copper probe connected to the 248

steel substrate and another probe placed onto the metallic Al pad. The breakdown voltage 249 occurs when visual shunts suddenly appear at the IL surface. This simple check also 250 251 verifies the IL quality by detection of defects such as small voids/cracks; if this were the case, the breakdown voltage occurs at very low values (<10V). To evaluate the maximum 252 253 voltage which the IL will have to endure, a value of 40V has been chosen considering 30cm x 30cm panels, typical 1cm width serial interconnected cells, output voltages of 254 255 current thin film commercial modules and by applying a security factor of 50% overvoltage. A second method to determine the dielectric behaviour of the ILs has been 256 257 through the measurement of the leakage current. Although this test requires a low current source measurement unit, it enables a quantification of the IL insulation. For these tests, 258 259 aluminium electrodes have been deposited in a thermal evaporator (Edwards 306). A 260 shadow mask was used to define an active area for the electrodes. A Keithley 237 High 261 Voltage Source Measurement Unit (SMU) was used to measure the leakage current between the back electrode and steel substrate. The bias range was selected from -50V to 262 +50V and the SMU is capable of measuring leakage current at a resolution of  $10^{-13}$ A. 263 264 Small contact areas were used (5mm diameter circle) and contacted using electrical 265 probing.

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### 267 2.3 PV technologies

#### 268 **2.3.1 Amorphous silicon**

Amorphous silicon solar cells were manufactured onto steel with an n-i-p a-Si:H 269 270 structure, instead of the more commonly used p-i-n junction configuration, which is widely adopted for transparent substrates (see Figure 1a and Figure 1b). The bottom and 271 top electrode materials have been reversed in order to improve their electrical 272 conductivity and the electron extraction. Therefore, a bottom electrode of aluminium (Al) 273 274 and indium tin oxide (ITO) was chosen. The Al and ITO layers were deposited by thermal 275 evaporation (Pfeiffer 500 System) and rf sputtering (AJA International, model ATC Orion 276 8HV), respectively. Both processes were performed at room temperature. ITO samples were measured for transparency using UV-NIR spectrophotometry (Avantes, model 277 AvaSpec2048-USB2) with the wavelength range from 400nm to 800nm. Transmittance 278 higher than 90% was achieved in all cases. ITO sheet resistance (R<sub>s</sub>) was determined by 279

the four-point probe method (Lucas-Signatone, model Pro4) and values of  $20\Omega/\Box$  and  $8\Omega/\Box$  respectively for back and front contacts.

282 The n-i-p a-Si:H layers were deposited by (Very-High Frequency) VHF-PECVD in a 283 cluster configuration system which has separate chambers for the deposition of intrinsic, 284 n-type and p-type layers in order to avoid cross contamination (Elettrorava, model V0714). The silicon deposition process was performed using a plasma gas reaction using 285 SiH<sub>4</sub> as the plasma gas and applying a power density of  $16 \text{mW/cm}^2$  at a fixed frequency 286 of 13.56MHz. The gas mixtures, the substrate temperature and the chamber pressure 287 288 during the n-i-p layers are detailed in previous work [9]. In order to achieve better extraction of the generated electrons, a silver grid busbar was deposited on the top ITO 289 290 electrode in the samples. All samples were made with an active area of 1cm<sup>2</sup>.

291 The performance of the a-Si:H TFSC was determined by measuring the power conversion efficiency (PCE) from current-voltage (I-V) curves generated by the TFSC devices under 292 global AM1.5G spectrum (1000W/m<sup>2</sup>, 25°C) solar simulator (Oriel, model 91193) 293 through the standard IEC 60904-3:2008. In parallel to a-Si:H TFSC grown on our steel/IL 294 295 samples, n-i-p inverted cells were also manufactured on glass substrate as a reference. This configuration allows us to benchmark the performance of PVs made on IL-coated 296 steel with those made on the more conventional glass substrate and provide information 297 298 to the PV community about the relative performance of PVs on steel as opposed to glass. 299 All reported performances are averaged from 6 devices.

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### 301 2.3.2 Organic Photovoltaics

302 OPVs were fabricated on IL coated steel substrates composed of an opaque bottom 303 electrode, a thin-film semiconductor, and a transparent top electrode (see Figure 1c). For 304 device fabrication, a similar process to the work of Ding et al. was used [21] with the following inverted layer structure: Steel-Al-Cr-ZnO/-3HT:PCBM-CLEVIOS HTL-305 306 AgNW. The IL coated substrates were used for the deposition of the solar cell. Al/Cr 307 metal back electrodes were thermally evaporated onto the steel/IL system through a 308 shadow mask in an Edwards 306 thermal evaporator. A zinc oxide electron transporting 309 layer was deposited from zinc acetate dehydrate (109mg) dissolved in 2-methoxyethanol 310 (1ml) and ethanolamine (0.03ml) solution. This was spin-coated on the metal electrode and annealed in the presence of atmospheric air at 150°C for the zinc acetate to calcinate 311

into zinc oxide. Initially, active layer blends using poly(3-hexylthiophene) (P3HT) and 312 [6,6]-Phenyl-C61-butyric acid methyl ester (PCBM) with weight ratios 5:4 were prepared 313 314 and mixed with chlorobenzene solvent with a concentration of 40mg/ml, and allowed to dissolve for 24 hours on a hot plate at 60°C. Samples were stored in a nitrogen atmosphere 315 316 glovebox ([O<sub>2</sub>] <1ppm, [H<sub>2</sub>O] <100ppm), where the active layer was applied by spincasting from the 60°C solution to form a 220nm layer. This is thicker than earlier work 317 and is required in order to ensure higher yield as the SiOx sol-gel layers create more 318 roughness prior to solar cell deposition. The active layer was annealed at 140°C for 30 319 320 minutes before the hole transport layer (HTL, i.e. Clevios HTL PEDOT) was spin-coated at 4000rpm. The transparent top electrodes were fabricated by spray coating PH1000 321 PEDOT:PSS (purchased from Ossila ltd., UK) and 0.5mg/ml silver nanowire (Ag NW) 322 (L-50, purchased from ACS Materials Inc, USA) in ethanol subsequently onto the HTL 323 324 in a fume hood through a shadow mask with an air brush. All samples were made with an active area of  $1 \text{ cm}^2$  and the results presented are averaged from 6 devices. 325

Alongside the OPVs on steel substrates, conventional inverted cells were manufactured 326 327 on ITO coated glass substrates. The properties of the ITO-glass were: Rs=18 $\Omega/\Box$ , transparency=84% with glass, transparency=94% without glass, and were purchased from 328 Xinyan Ltd. The samples were cleaned using deionised water, acetone and isopropanol 329 in an ultrasonic cleaner and then treated in a UV-ozone reactor with oxygen plasma for 330 331 10 minutes and were then used to fabricate OPVs with the following layer structure: ITO/ZnO/P3HT:PCBM/CLEVIOS HTL/Ag. Except for the ITO and the thermally 332 333 evaporated Ag top electrode, all the other layers were the same as opaque steel substrate 334 cells. As with the a-Si:H cells, the reference sample provides a comparison between PVs 335 made on steel substrates with conventional processing routes. In addition, testing was conducted using the methodology explained in the a-Si section. 336

### 337 3. Results and discussion

### 338 **3.1** Levelling and barrier properties of ILs on steel

The three IL coatings were applied onto the four selected steels types, leading to 12 steel/IL combinations. The optimised deposition procedure is highlighted in section 2 for the different layers. The measured thicknesses of the IL coatings were independent of the steel substrate and were between 3-4µm for sprayed sol-gel coatings, ~30µm for the BlueInk and ~70µm for SU8. Thicknesses were initially measured using profilometry,

but confirmed with cross-sectional field emission secondary electron microscopy (FE-344 SEM) as shown in figure 2. The images show the consistency of the IL layers with low 345 346 surface roughness and are virtually defect free in the bulk. For the organic layers, a 347 moderate optimisation process was needed in order to apply the materials onto steel 348 substrates. However, for sol-gel coatings, a significant optimisation was required to ensure that the right combination of formulation and process spray parameters were used 349 350 to obtain a consistent and robust coating. However, once fully optimised, the process was readily reproducible and the results explained herein are based upon the optimised 351 352 deposition processes reported in section 2.

353 For all IL coatings, it is observed that a significant reduction in surface roughness is 354 achieved when compared to the initial roughness of the substrate. Figure 3 shows the measured average roughness ( $R_a$ , Figure 3(a)) and peak-to-valley roughness ( $R_z$ , Figure 355 356 3(b)) for all the systems, denoting a clear reduction of these parameters when the IL are 357 deposited. Based upon results conducted for this paper, we estimate that a reduction of Ra 358 to <60nm and R<sub>z</sub> below <300nm is needed for high performing a-Si:H and OPV solar cell 359 deposition. However, the performance of OPVs seem more sensitive to high roughness, so in this case SU8 represents the best choice since this coating material has led to 360 R<sub>a</sub><15nm and R<sub>z</sub><90nm. 361

Concerning dielectric isolation, Table II summarizes the obtained results for all the steel/IL systems in terms of leakage current after the voltage breakdown test. As it can be seen, leakage currents are below 50nA/cm<sup>2</sup> for all the samples.

Further studies were conducted to evaluate whether the IL layers limit the impurity diffusion from the steel into the PV device. Figure 4 shows qualitative depth profiles of the steel substrates coated with the  $SiO_x$  sol-gel IL and an Al electrode to replicate the back contact of a solar cell. This electrode has been deposited in order to study reverse diffusion from the back contact through the  $SiO_x$  layer, and potentially into the solar cell.

For each steel/SiO<sub>x</sub>/Al system, a comparison between a non-annealed and an annealed process has been carried out. The annealing process was dictated by the thermal processes needed for the TFSC technologies considered in this work; therefore, the timetemperature cycle (150min at 210°C) for a-Si:H has been selected as the annealing cycle because it represents the most demanding annealing condition. For each qualitative depth profile, the Al layer shows an abrupt interface with the  $SiO_x$ coating. As the sputtering time increases, there is an increase in the silicon and oxygen content; an increase in carbon is also observed, owing to the PEG releasing agent that has not been fully degraded at the 210°C curing temperature.

379 Related to the DC01, DX51D+AS and AISI430 substrates, it is clearly observed that no 380 steel element (Fe, Cr) and Al/Si elements from the metallic coating are diffusing into the 381 SiO<sub>x</sub> sol-gel, demonstrating that this IL limits the diffusion of unwanted impurities from 382 the steel into the PV structure. Concerning the DX51D+Z substrate, a minor diffusion of 383 the zinc is present, although this is unlikely to interfere with the Al back contact due to 384 the low intensity and penetration depth. It is also observed that no diffusion of Al into the 385 steel substrates is apparent, so it appears that the  $SiO_x$  sol-gel layer does act as an ionic blocking layer in both directions. These qualitative in-depth profiles also show the 386 387 levelling effect of the  $SiO_x$  coating. All the profiles possess an abrupt interface between 388 the Al and SiO<sub>x</sub>, but the corresponding SiO<sub>x</sub>/steel interface is extended indicating a much 389 rougher surface finish on the steel.

The anti-diffusion behaviour of the organic coatings, i.e. the BlueInk, has been also 390 studied under the same experimental conditions as above. For this coating, the elemental 391 identification is much more complex due to the highly insulative behaviour of the coating 392 393 which limits the signal into the mass spectrometer until the depth profiling has reached 394 the steel substrate. However, it is possible to infer from the data that no elements from 395 the steel are diffusing through the dielectric, which is evidenced by the paucity of signals 396 detected in between the steel and surface, demonstrating that the BlueInk also acts as a 397 good anti-diffusion barrier. For SU8, these characterizations have not been carried out 398 due to the high charging as a result of the highly insulative properties of the layer.

399 **3.2 Dielectric behaviour of ILs** 

The dielectric behaviour of the ILs has been evaluated by measuring the leakage current and by detection of a breakdown potential. Through breakdown tests, it was shown that the dielectric coatings (sol-gel, *BlueInk* and SU8) passed well above the threshold of 40V. In the case of sol-gel samples, values of 53V were obtained. *BlueInk* coatings showed breakdown potentials above 500V. As qualitative test, the leakage current was measured by voltage sweeping from -40V to +40V in steel/IL systems with evaporated silver or aluminium electrodes. Table II shows the achieved values for all the tested samples. This supports the breakdown tests confirming that these ILs are suited as electrical insulator
layers for BIPVs on steel substrates, with few pin holes present in the films.

### 409 **3.3 Photovoltaic cells**

Solar cells (1cm<sup>2</sup>) were manufactured on all four types of steel and three different IL 410 411 coating combinations. This was undertaken for both a-Si:H solar cells and OPVs. The 412 results are summarised in Table III and example current density-voltage (JV) 413 characteristics are shown for solar cells manufactured on SiO<sub>x</sub>-coated AISI430 in figure 414 5 under AM1.5G illumination. It is worth noting that the efficiencies of both a-Si:H solar 415 cells and OPVs are slightly lower than the state of the art in this field. The reason for this is twofold; firstly the solar cells are made on relatively large areas (1cm<sup>2</sup>) so are more 416 417 representative of module performance; secondly the device processing could be further 418 optimised for this configuration.

419

### 420 3.3.1 Performance of a-Si:H cells on IL-coated steel

421 Solar cells based on a-Si:H were successfully deposited in steel/IL systems with SiOx solgel as the IL. As shown in Table III, a relative difference of less than 10% was found 422 423 when compared to a solar cell made on the reference (glass) substrate using the same experimental procedure. These results confirms the suitability of the IL/steel substrate for 424 425 a-Si:H solar cell integration. Although this result had been achieved before [9], it is important to remark that, in this case, the layer was deposited from an upscale process 426 427 using a single spray step and a high speed curing cycle, instead of a three dip coating processes followed by a 1h30 thermal treatment. 428

429 In the case of organic coatings (BlueInk and SU8), the steel/IL systems were firstly introduced in a PECVD high vacuum chamber in order to evaluate possible desorption of 430 431 organic compounds that could induce future delamination of the solar cells. When the 432 steel/IL systems with the BlueInk IL was introduced into the vacuum system, a loss of one order of magnitude in vacuum pressure resulted  $(2.1 \times 10^{-6} \text{ Torr instead of the base})$ 433 pressure of 2.0x10<sup>-7</sup> Torr). A high vacuum treatment at 180°C was carried out for 2 hours 434 435 within the chamber. This thermal treatment allowed the improvement of the vacuum in the PECVD chamber to values close to  $3.1 \times 10^{-7}$  Torr, which is within the limits of the 436 deposition window. Subsequently, the a-Si solar cells were deposited using the same 437

experimental procedure as for those made onto the SiO<sub>x</sub> sol-gel examples. As shown in
Table IV, it has been possible to manufacture working cells. However, the obtained
efficiencies are around 1.67%, much lower than the efficiencies corresponding to the
glass reference. This result proves the viability of *BlueInk* as an IL for a-Si:H deposition,
although the roughness appears to limit the values of efficiency, in particular showing a
relatively low fill factor and poor shunt resistance.

Steel/IL samples using the SU8 IL layer were also introduced into the PECVD high vacuum chamber. However, a high desorption was registered just after the sample was introduced into the PECVD chamber (the pressure rose to  $1.2 \times 10^{-5}$  Torr from the limit of  $2.0 \times 10^{-7}$  Torr). As a result of the poor desorption properties, it was judged that the SU8 epoxy was not suitable for a-Si:H TFSC.

### 449 3.3.2 Performance of OPVs on IL-coated steel

Table III reports the power conversion efficiencies achieved for OPVs on the four steels 450 451 coated with SiO<sub>x</sub> sol-gel IL by spray coating. It is evident that the efficiencies achieved on steel (2.00-2.40%) are lower than achieved on a standard OPV fabricated on glass 452 453 (2.90%). The results provide a comparison of the same active layer material system, but very different architecture owing to the different substrates and different direction of 454 455 irradiation onto the cell. Despite the lower efficiency, the result highlights the compatibility of OPV onto steel substrate with a scalable SiO<sub>x</sub> sol-gel IL. Glass is a low-456 457 cost and slightly higher performing option but is not R2R compatible which is a disadvantage for OPVs, as most groups tend to fabricate OPVs from solution processing 458 459 on R2R processing lines. In the case of the SU8 IL layer, the efficiency achieved is 460 relatively similar to that achieved on the SiO<sub>x</sub> IL (2.42%). OPVs are unlikely to be made 461 commercially onto glass substrates, as glass adds a limitation to two of the key advantages 462 which the OPV technology provides: flexibility and low embodied energy per module. 463 Therefore, a more commercially relevant comparison of OPV performance is conducted relative to substrates such as polyethylene terephthalate (PET) or polyethylene 464 naphthalate (PEN), as is shown in Table IV. In comparison, the performance of OPVs on 465 PEN and PET is 2.31% and 2.2%, respectively. By comparison, OPVs made on steel have 466 467 an intermediate efficiency; they are not better than those made on glass, but appear to work better than those manufactured on plastic substrates. Concerning organic coatings, 468 the use of *BlueInk* led to unsuccessful results for the manufacturing of OPVs. This is 469

likely to be due to the high surface roughness of this layer, which this group estimated asbeing twice that required for the deposition of OPV.

472

#### 473 **3.4 Economic viability**

A cost analysis taking into account both the SiO<sub>x</sub> sol-gel (spray process) and the *blue ink* 474 (screen printing process) ILs was finally performed in order to report the economic 475 viability of the Steel/IL prototypes. The detailed study of the economic feasibility of both 476 IL is reported in a previous work [26]. In this work, the process has been extended to 477 478 ascertain the costs involved in manufacturing a new BIPV product adopting a bottom up approach in alignment with Anderson [27], where each of the individual cost elements 479 (materials, manufacturing fixed costs, plant capacity and operations/maintenance) were 480 identified and included within the cost model. The cost analysis assumes the utilisation 481 of a modern R2R production facility with a manufacturing plant capacity of 30 MW/year 482 [28] to assure the most efficient and cost-effective means to develop the BIPV products. 483

In that sense, a feed rate for both IL materials has been estimated at 12m/min, taking 6.9 hours to process a 1500m<sup>2</sup> roll, or 2.3 hours for a 500m<sup>2</sup> roll (roll size dependant on material thickness). After estimations of the consumable investment  $(0.12\text{€/m}^2 \text{ for } blue$ *ink* and  $0.23\text{€/m}^2$  for SiO<sub>x</sub> sol-gel), the labour  $(0.52\text{€/m}^2)$ , the electricity  $(0.15\text{€/m}^2)$  and the materials costs including wastage  $(1.80\text{€/m}^2 \text{ for } blue \text{ ink} \text{ and } 0.33\text{€/m}^2 \text{ for SiO}_x \text{ sol-gel})$ , gel), total processing costs of  $2.60\text{€/m}^2$  for Blue Ink and  $1.24\text{€/m}^2$  for SiO<sub>x</sub> sol-gel were calculated.

491

### 492 **4** Conclusions

The development of electrically insulative, ionic blocking, planarising 'intermediate layers' (ILs) opens the possibility of using low-cost steels for the deposition of TFSC and, in addition, allows for monolithically interconnected cells on this substrate. The results have been achieved using a wide range of low cost steels (bare low carbon, hot-dip low carbon and ferritic stainless) using an inorganic sol-gel coating and two commercial organic materials, a dielectric ink and a photoresist. In the case of sol-gel IL layers, a-Si:H solar cells have been manufactured with efficiencies ( $\eta = 4.59\% - 5.56\%$ ) close to those achieved on a reference glass substrate ( $\eta = 5.51\%$ ). The sol-gel/steel combination has been used as a substrate for OPV manufacturing, obtaining efficiencies between 2.00% and 2.40%, marginally lower than the efficiency obtained onto glass ( $\eta = 2.90\%$ ). These differences have been attributed to surface roughness of the coating ( $R_a = 30nm - 60nm$ ) and different architecture of the device.

When organic coatings have been considered, SU8 coatings show a significant 506 planarizing effect, with mean average roughness below 20nm. This enabled the 507 508 deposition of OPVs on steel/SU8 systems with high efficiency ( $\eta = 2.29\% - 2.42\%$ ) when compared to a flexible substrate reference (PEN,  $\eta = 2.31\%$ ). In the case of a-Si:H, 509 510 desorption of this coating under initial vacuum conditions has not allowed the deposition of these cells. *BlueInk* organic coatings represent an alternative approach to obtain high 511 512 dielectric coatings by means of simple and inexpensive deposition processes (in particular, screen printing). However, the results show that further improvements in terms 513 514 of planarity and roughness are still required for the deposition of TFSCs. In the first case, 515 the a-Si:H cells show low fill factor (FF=30%) and, consequently, low efficiencies when compared to glass standard. 516

517

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522

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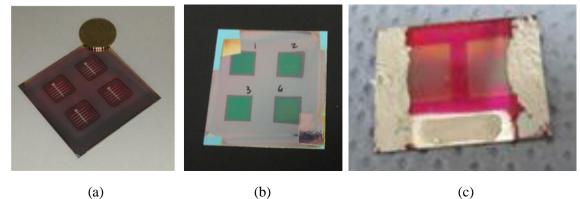
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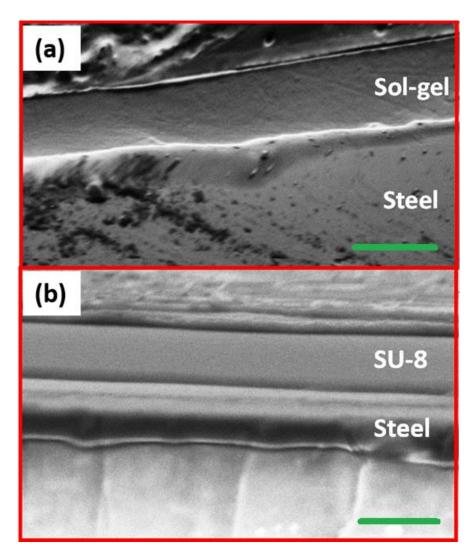
# 604 **Table captions**

- Table I. Chemical composition of selected steel substrates samples used for thiswork
- **Table II**. Leakage currents (in nA) corresponding the steel/IL systems developed in thiswork
- 609 **Table III**. Photovoltaic performance parameters obtained from illumination under
- 610 1 Sun AM1.5G spectrum for the a-Si:H and OPV cells on different steel/IL
- 611 systems
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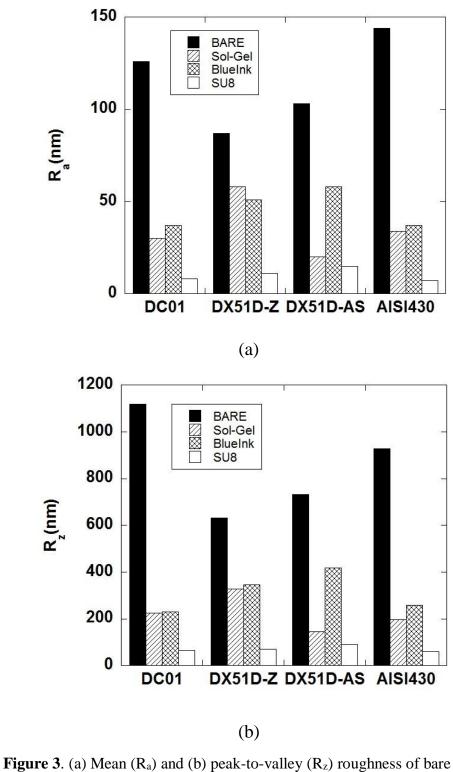
- 616 (a) (b) (c)
  617 Figure 1. (a) a-Si:H solar cells deposited on AISI430/SiO<sub>x</sub> sol-gel (b) onto BlueInk and
- 618 (c) Organic photovoltaic deposited onto AISI430/SU8

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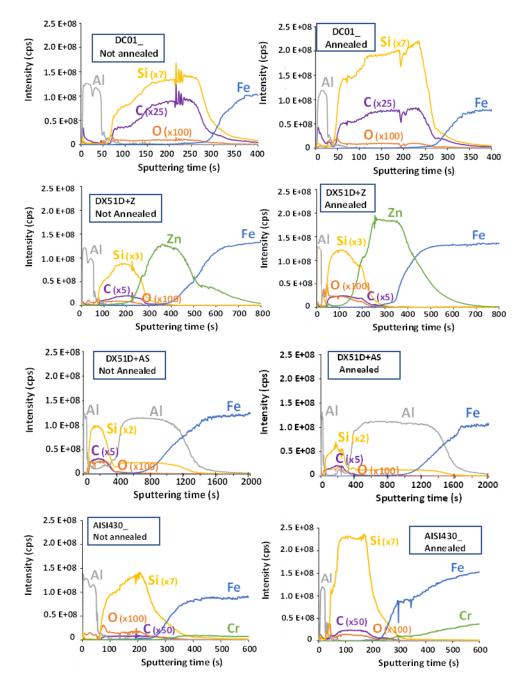




- **621** Figure 2. FE-SEM cross sectional image of AISI430 steel samples coated with (a)  $SiO_x$
- 622 sol-gel (scale bar =  $3\mu m$ ) and (b) SU8 intermediate layers (scale bar =  $60\mu m$ )



- Figure 3. (a) Mean (R<sub>a</sub>) and (b) peak-to-valley (R<sub>z</sub>) roughnes
  selected steels and steel/IL systems developed in this work



633

**Figure 4** Qualitative depth profiles obtained using glow discharge time of flight mass spectroscopy (GD-ToF-MS) of non annealed and annealed for all steels/SiO<sub>x</sub> sol-gel samples used in this work, with Al top electrodes to replicate the structure of the solar cell. The SiO<sub>x</sub> layer shows extremely good barrier layer performance.

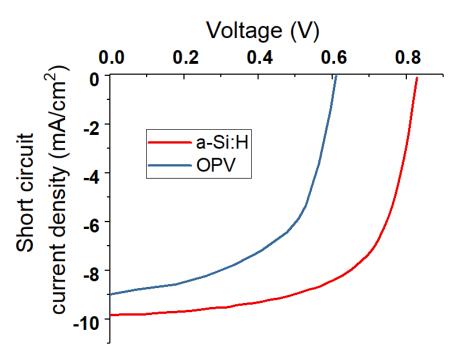




Figure 5. Sample J–V curves of solar cells using data of a-Si:H solar cells and
OPV onto AISI430 substartes after a SiO<sub>x</sub> sol-gel IL has been applied

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# Table I. Chemical composition of selected steel substrates

|     | Material  | Chemical composition %(wt.) |       |       |             |             |           |       |  |
|-----|---|-----------------------------|-------|-------|-------------|-------------|-----------|-------|--|
|     |   | С                           | Si    | Mn    | Р           | S           | Cr        | Ti    |  |
| #01 | Bare Steel<br>(DC01)                            | ≤ 0.12                      | ≤ 0.3 | ≤ 0.6 | ≤ 0.045     | $\le$ 0.045 | -         | -     |  |
| #02 | Hot-dip zinc coated<br>(DX51D+Z) <sup>1</sup>   | ≤ 0.18                      | ≤ 0.5 | ≤ 1.2 | ≤ 0.12      | ≤ 0.045     | -         | ≤ 0.3 |  |
| #03 | Hot-dip Al-Si coated<br>(DX51D+AS) <sup>2</sup> | ≤ 0.18                      | ≤ 0.5 | ≤ 1.2 | ≤ 0.12      | ≤ 0.045     | -         | ≤ 0.3 |  |
| #04 | Stainless Steel<br>(AISI430)                    | $\leq 0.08$                 | ≤ 1.0 | ≤ 1.0 | $\leq 0.04$ | ≤ 0.03      | 16.0-18.0 | -     |  |

648¹Hot-dip Zn: Zn≥98%649²Hot-dip Al-Si: Al 85.5

<sup>2</sup>Hot-dip Al-Si: Al 85.5%-88.5% + Si 9%-11% + Fe 2.5%-3.5%

|     |          | Leakage current (nA/cm <sup>2</sup> ) |                 |            |            |             |             |  |  |
|-----|----------|---------------------------------------|-----------------|------------|------------|-------------|-------------|--|--|
|     | Material | Sol-gel<br>(Ag)                       | Sol-gel<br>(Al) | BI<br>(Ag) | BI<br>(Al) | SU8<br>(Ag) | SU8<br>(Al) |  |  |
| #01 | DC01     | 35.17                                 | 35.00           | -          | -          | 27.29       | 41.58       |  |  |
| #02 | DX51D+Z  | 36.29                                 | 36.25           | -          | -          | 18.96       | 30.08       |  |  |
| #03 | DX51D+AS | 31.00                                 | 30.83           | -          | -          | 16.17       | 23.13       |  |  |
| #04 | AISI430  | 25.92                                 | 29.04           | -          | -          | 11.54       | 12.46       |  |  |

652 Table II. Leakage currents (in nA/cm<sup>2</sup>) corresponding the steel/IL systems
653 developed in this work

Table III. Characteristic parameters obtained from current-voltage curves
corresponding a-Si:H and OPV cells on different steel/IL systems. Averages
are taken from 6 devices for all reported in this work and standard
deviations are also reported

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|-----|
|-----|

|      |           | a-Si:H*                          |             |           |           | Organic PV                   |              |           |            |  |
|------|-----------|----------------------------------|-------------|-----------|-----------|------------------------------|--------------|-----------|------------|--|
|      |           | Jsc<br>(mA/c<br>m <sup>2</sup> ) | Voc<br>(mV) | FF<br>(%) | η (%)     | Jsc<br>(mA/cm <sup>2</sup> ) | Voc<br>(mV)  | FF<br>(%) | η (%)      |  |
|      | Reference | 11.03                            | 813±3       | 55±1      | 5.51±     | 9.88                         | 590 ±2       | 59        | 2.90       |  |
|      | (glass)   | ±0.35                            |             |           | 0.21      | ±0.20                        |              | $\pm 4.0$ | ±0.34      |  |
|      | DC01      | 10.62                            | 839±4       | 56±4      | $5.56\pm$ | 8.46                         | $560 \pm 5$  | 45        | 2.15       |  |
|      |           | ±0.94                            |             |           | 0.16      | ±0.30                        |              | ±4.2      | ±0.46      |  |
| SiO  | DX51D+Z   | 10.22                            | 832±9       | 58±4      | $5.41\pm$ | 8.21                         | $550 \pm 3$  | 44        | 2.00       |  |
| x SG |           | ±0.55                            |             |           | 0.12      | $\pm 0.40$                   |              | ±4.9      | ±0.27      |  |
| x 5G | DX51D+A   | 10.65                            | 835±7       | 47±2      | 4.59*     | 8.70                         | $550 \pm 3$  | 47        | 2.23       |  |
|      | S         | ±0.21                            |             |           | *±0.1     | ±0.40                        |              | ±2.9      | ±0.25      |  |
|      |           |                                  |             |           | 6         |                              |              |           |            |  |
|      | AISI430   | 9.92±                            | 820±17      | 61±3      | $5.53\pm$ | 9.20                         | 530 ±3       | 48        | 2.40       |  |
|      |           | 0.61                             |             |           | 0.26      | ±0.50                        |              | ±6.0      | ±0.52      |  |
|      | DC01      | -                                | -           | -         | -         |                              |              |           |            |  |
|      | DX51D+Z   | -                                | -           | -         | -         |                              |              |           |            |  |
| BI   | DX51D+A   | -                                | -           | -         | -         |                              |              |           |            |  |
| BI   | S         |                                  |             |           |           |                              |              |           |            |  |
| DI   | AISI430   | 6.93±                            | 750±82      | 29±1      | $1.67\pm$ | 7.63                         | 510 ±5       | 38        | 1.48       |  |
|      |           | 1.12                             |             |           | 0.43*     | ±0.22                        |              | ±4.0      | $\pm 0.20$ |  |
|      |           |                                  |             |           | *         |                              |              |           |            |  |
|      | Reference |                                  |             |           |           | 9.01                         | $570 \pm 2$  | 45        | 2.31       |  |
|      | (PEN)     |                                  |             |           |           | ±0.18                        |              | $\pm 5.0$ | ±0.30      |  |
|      | DC01      |                                  |             |           |           | 9.54                         | $546 \pm 10$ | 55        | 2.42       |  |
|      |           |                                  | D           | • •       |           | ±0.19                        |              | $\pm 5.8$ | ±0.22      |  |
| CTIO | DX51D+Z   | Desorption at<br>required vacuum |             |           | 8.90      | $546 \pm 8$                  | 47           | 2.29      |            |  |
| SU8  |           |                                  | required    |           |           | ±0.20                        |              | ±6.0      | ±0.31      |  |
|      | DX51D+A   |                                  | ievo        |           |           | 9.01                         | $540 \pm 10$ | 47        | 2.30       |  |
|      | S         |                                  |             |           |           | ±0.29                        |              | ±3.0      | ±0.20      |  |
|      | AISI430   |                                  |             |           |           | 8.94                         | 540 ±0.2     | 49        | 2.35       |  |
|      |           |                                  |             |           |           | ±0.09                        |              | ±2.5      | ±0.18      |  |

661 \*a-Si:H area of 1cm<sup>2</sup> without silver grid and 0.9cm<sup>2</sup> with silver grid

\*\*no silver grid Irradiance of 0.9W/cm<sup>2</sup> for the a-Si:H measurements

